

# Call for Papers

## The 41<sup>st</sup> European Mask and Lithography Conference

# EMLC 2026

Volkshaus Jena, Germany • June 22 – 24, 2026

[www.emlc-conference.com](http://www.emlc-conference.com)

The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) in cooperation with BACUS, PMJ, and SPIE are pleased to announce the

41<sup>st</sup> European Mask and Lithography  
Conference, EMLC 2026  
at the Volkshaus Jena, Germany,  
June 22 – 24, 2026

The 2 ½ days conference is focused on state of the art mask and lithography technologies, comprising all aspects of manufacturing, processing, qualification as well as application of masks and lithography equipment for DUV, EUV, Nano Imprint and new and emerging lithography technologies.

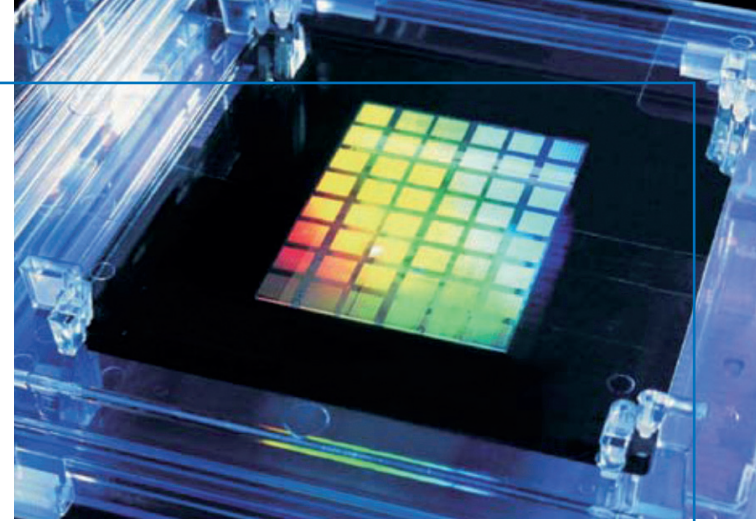
This annual conference brings together scientists, researchers and engineers from around the world to present papers at the forefront in their scope of works. The EMLC serves as a place where both specialists from industry and advanced research as well as equipment and software providers come together, may take part in technical discussions benefit from networking.

### Tutorials and Technical Exhibition

As part of the conference program a tutorial session will be scheduled.

In parallel to the technical program a commercial exhibition will be held.

Further information will be announced at the EMLC webpage ([www.emlc-conference.com](http://www.emlc-conference.com)) shortly.



Picture: Courtesy of Toppan Photomasks

### Abstract and Manuscript Information

Experts from industry and research institutes wishing to present the results of their recent research are cordially invited to submit a paper. Accepted submissions will be presented in either oral or poster sessions.

Please submit a PDF formatted abstract in English with a length of two pages (400 – 600 words) including figures, tables & references showing summary, motivation, approach and results. The paper should be headed by title, authors' names and affiliations.

Abstracts with no new research/development or commercial content will not be accepted.

All accepted abstracts (i.e. the 2-page PDF file) will be made available in digital form to the conference participants, one week prior to the conference start.

EMLC is cooperating with SPIE and uses the SPIE tool for abstract submission and reviewing.

After acceptance of the abstract, authors are invited to submit a manuscript for the SPIE Proceedings of the EMLC 2026 Conference. By submitting your manuscript, the SPIE Copyright agreement is accepted.

In order to submit your abstract to the SPIE tool, please find instructions at [www.emlc-conference.com](http://www.emlc-conference.com)

### Important Dates

**27 January 2026 .. submission of abstracts**

**14 April 2026 ..... notification of acceptance**

**25 June 2026 ..... submission of manuscripts**

### Mask Manufacturing and Mask Business

- Photomasks and EUV masks
- Mask Data Preparation
- Pattern Generation: Laser and Electron single & multi-beam mask writing
- Photomask Processes & Materials inc. cleaning
- Defect Inspection & Repair
- Mask Handling, Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Mask Business & Future Mask Demand
- Curvilinear mask: data preparation, patterning & metrology

### Lithographic Systems and Processes

- i-line, DUV, Immersion, EUV exposure systems
- Optical resolution enhancement techniques including OPC, free-form illumination, Source-Mask-optimization (SMO), Inverse Lithography Technology (ILT) and AI enhancement
- Material-and process driven Resolution Enhancement techniques including new resist developments, Multiple Patterning and Chemical Shrinking
- Lithography process control & pattern fidelity
- Computational lithography – and etch-simulation, Inverse Lithography Technology (ILT)
- Sustainability

### Emerging Mask and Lithography Technologies

- High- and Hyper-NA EUV-Lithography including Masks, Materials Processes and Infrastructure.
- Future light sources
- Directed Self-Assembly (DSA) including High Chi Materials, Defectivity Control and new Processes
- Direct Write / Maskless Technologies including Laser and electron Multi-Beam Technologies
- Nano-Imprint Lithography (NIL), Soft Lithography and Microprinting
- Two-photon lithography

### Metrology Tools and Technologies for Mask and Lithography Processes

- High precision CD metrology on large structures
- Placement accuracy measurement of structures in critical areas
- Film height and SWA measurements in small trenches
- Usage of AI to enhance uniformity measurements

### Emerging Applications

- Non-IC Applications including photonics, bio – and life science applications, flat panel displays & MEMS, fabrication of meta surfaces, VR/AR
- Lithography for Quantum Technology
- Lithography for future AI
- Advanced packaging
- 3D patterning & integration incl. backside patterning

### Conference Chairs

*Stolberg, Ines*, Vistec Electron Beam, Jena (Germany)  
*Finders, Jo*, ASML, Veldhoven, (The Netherlands)

### Conference Co-Chairs

*Connolly, Brid*, Tekscend Photomask Germany GmbH, Dresden (Germany)  
*Hayashi, Naoya*, DNP, Saitama (Japan)

### Program Chairs

*Loeschner, Hans*, IMS Nanofabrication, Brunn am Gebirge & Vienna (Austria)  
*Bottiglieri, Gerardo*, ASML, Veldhoven (The Netherlands)  
*Erdmann, Andreas*, Fraunhofer IISB, Erlangen (Germany)  
*Peters, Jan Hendrik*, bmbg Consult, Radebeul (Germany)

### Honorary President

*Behringer, Uwe*, UBC Microelectronics, Ammerbuch (Germany)

### Further Members

*Abboud, Frank E.*, Intel - IMO, San José, CA (USA)  
*Ehrmann, Albrecht*, Carl Zeiss SMT, Oberkochen (Germany)  
*Fay, Aurélien*, CEA-Leti, Grenoble (France)  
*Galler, Reinhard*, EQUIcon, Jena (Germany)  
*Hai, Xueying*, Mycronic AB, Täby (Sweden)  
*Jefferies, James*, HOYA Europe, London (UK)  
*Le Gratiet, Bertrand*, STMicroelectronics, Crolles (France)  
*Levinson, Harry J.*, HJL Lithography, Saratoga, CA (USA)  
*Maas, Raymond*, ASML, Veldhoven (The Netherlands)  
*Maly, Enrico*, Photronics MZG, Dresden (Germany)  
*Matsumoto, Hiroshi*, NuFlareTechnology, Yokohama (Japan)  
*Muehlberger, Michael*, Profactor, Steyr-Gleink (Austria)  
*Noack, Nico*, AMTC, Dresden (Germany)  
*Pain, Laurent*, CEA-Leti, Grenoble (France)  
*Ronse, Kurt*, IMEC, Leuven (Belgium)  
*Scheruebl, Thomas*, Carl Zeiss SMT, Jena (Germany)  
*Schnabel, Ronald*, VDE e.V., Offenbach am Main (Germany)  
*Schneider, Jens*, Infineon Technologies, Dresden (Germany)  
*Schuch, Nivea*, Applied Materials, Grenoble (France)  
*Sundermann, Frank*, STMicroelectronics, Crolles (France)  
*Tchikoulaeva Anna*, Lasertec USA Inc., German Branch, Dresden (Germany)  
*Tschinkl, Martin*, Tekscend Photomask Germany GmbH, Dresden (Germany)  
*Varga, Ksenija*, EV Group, Florian am Inn (Austria)  
*Wurm, Stefan*, ATICE LLC, Albany, NY (USA)  
*Zeggaoui, Nassima*, Siemens Industry Software, Meylan (France)  
*Zurbrick, Larry*, Keysight Technologies, Santa Clara (USA)

### EMLC 2026 Organizer

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